



Product Change Notification

111022 - 01

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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Product Change Notification

Change Notification #: 111022 - 01
Change Title: Intel® Desktop Board DH61BE, GbE LAN, Boxed and Bulk
PCN 111022-01, Product Material, Product Design
Change to NEC USB 3.0 stepping, iTE* PCIe to PCI bridge stepping and BIOS Update
Reason for Revision: Remove I/O shield change
Date of Publication: December 02, 2011

Key Characteristics of the Change:

Product Material and Product Design

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	Nov 21, 2011
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Description of Change to the Customer:

Reason for Revision: Remove I/O shield change

Intel has implemented the following changes:

1. **The following change will not be implemented at this time:** Improved I/O shield type from tab-lock to dimple type as shown below:
2. To prevent a potential risk to have material shortage on NEC USB 3.0 the part will be changed from A to the F1 stepping.
3. The iTE* PCIe to PCI bridge will be changed from the C version to E Stepping to increase compatibility.
4. The BIOS will be updated from BEH6110H.86A.0020 to BEH6110H.86A.0032. To access the release notes or get a copy of the BIOS for evaluation, go to <http://downloadcenter.intel.com>.

Customer Impact of Change and Recommended Action:

It has been observed that the change for the USB3.0 controller and the iTE* PCIe to PCI bridge reports a "New device detected" in some operating systems. Microsoft* Windows will display a message and automatically install the necessary drivers; however customers may wish to update their OS image to avoid the message.

It is recommended that customers evaluate the new BIOS to ensure a smooth transition. Intel validation of a new board revision does not include testing with older versions of the BIOS. This change is not expected to cause a change to the Microsoft Windows* operating system's

software driver stack. New board revisions cannot be downgraded to an older BIOS version.

These changes have been thoroughly evaluated to ensure that there are no quality, reliability or functional implications to our customers. Intel is not recommending additional qualification of these changes on platforms received from Intel.

Intel will attempt to deplete pre-conversion material before shipping post-conversion material but there is a possibility of Intel shipping mixed inventory. Therefore, customers will need to manage and migrate to the post-conversion material as soon as possible.

Milestone dates are estimates and subject to change based on business and operational conditions.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change AA	Post Change AA
BOXDH61BEB3	915110	G14062-207	G14062-208
BLKDH61BEB3	915111	G14062-207	G14062-208
LADH61BEB3	915112	G14063-207	G14063-208

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
October 4, 2011	00	Originally Published PCN
December 2, 2011	01	Remove I/O shield change